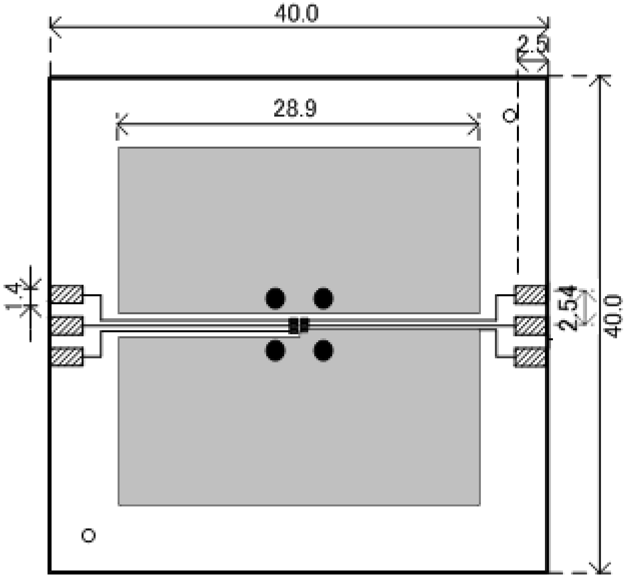
●USPN-6B01 Power Dissipation

Power dissipation data for the USPN-6B01 is shown in this page.
The value of power dissipation varies with the mount board conditions.
Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition : Mount on a board
Ambient : Natural convection
Soldering : Lead (Pb) free
Board : Dimensions 40mm x 40 mm (1600mm2)
Copper (Cu) traces occupy 50% of the front and 50% of the back.
VSS pin is tied to the copper traces
Material : Glass Epoxy（FR-4）
Thickness : 1.6mm
Through-hole : 4 x 0.8 Diameter



Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature

Board Mount (Tjmax=125℃)

Ambient Temperature (℃)	Power Dissipation Pd (mW)	Thermal Resistance (℃/W)
25	600	166.67
85	240